**Product Description**

My-T-Bond® 2738 is a 2K-Epoxy room temperature curing, thixotropic adhesive; it bonds and repairs a wide variety of materials. My-T-Bond® 2738 offer superior thermal shock resistance, mechanical, electrical and impact resistant properties.

**Applications:**
- Used for industrial assemblies for multi-purpose applications
- Suitable for bonding and potting electronic components.
- Used for bonding of metals, electronic components, GRP structures.

**Properties**

<table>
<thead>
<tr>
<th>Technology</th>
<th>Epoxy</th>
</tr>
</thead>
<tbody>
<tr>
<td>Components</td>
<td>2K</td>
</tr>
<tr>
<td>Mix ratio by weight</td>
<td>100 : 80</td>
</tr>
<tr>
<td>Part A: Part B</td>
<td>1 : 1</td>
</tr>
<tr>
<td>Mix ratio by Volume</td>
<td>1 : 1</td>
</tr>
<tr>
<td>Appearance</td>
<td>Black</td>
</tr>
<tr>
<td>Cure</td>
<td>Room Temperature</td>
</tr>
<tr>
<td>Pot life</td>
<td>3 min</td>
</tr>
<tr>
<td>Tack free Time</td>
<td>10 min</td>
</tr>
<tr>
<td>Operating temperature</td>
<td>-30 °C to 150°C</td>
</tr>
<tr>
<td>Applications</td>
<td>Bonding, potting, encapsulation</td>
</tr>
<tr>
<td>RoHS</td>
<td>Compliant</td>
</tr>
<tr>
<td>REACH</td>
<td>Compliant</td>
</tr>
</tbody>
</table>

**Properties of Material**

<table>
<thead>
<tr>
<th>Properties</th>
<th>Part A (Resin)</th>
<th>Part B (Hardener)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Colour</td>
<td>Black</td>
<td>Slight Yellow</td>
</tr>
<tr>
<td>Sp. Gravity @ 25±2 °C</td>
<td>1.2±0.1</td>
<td>1.13±0.03</td>
</tr>
<tr>
<td>Brookfield Viscosity@ 25±2°C, Spindle # 6, @ 20 rpm.</td>
<td>13000-15000 CP</td>
<td>10000-16000 cP</td>
</tr>
</tbody>
</table>

**Adhesive Properties**

- Lap Shear Strength, ASTM D 1002; After 24 hrs
  - Steel : 10-13 N/mm²
  - Aluminium : 6-8 N/mm²
  - ABS : 1.5-2.5 N/mm²
  - Nylon : 1.3-2.5 N/mm²
  - Styrene : 1.2-2.4 N/mm²
- Impact Strength, ASTM D-950 : >35 N.mm/mm²
- Hardness ASTM D-2240, Shore D : 75

**Hot Strength**

- Test : Lap Shear Strength, ASTM D1002
- Substrate : Steel
- Cure : 24 hrs @ 25±2 °C
- Tested at temperature indicated

**Thermal Cycling**

- Test Procedure : Substrate (Steel) cure as per cure procedure indicated above and then subjected to 120 to -30 °C alternatively. (Half hours at 120 °C and then subjected to half hours at -30 °C, such Six cycles were performed).

- Substrate : Steel
- Cure Procedure : 24 hrs @ 25±2 °C
- Strength : % Initial Strength Retained
  - Lap Shear : 100
  - Impact Strength : 100
Directions for Use

- For best performance, clean substrates to remove dust, grease, oil etc.

For Hand use:

- To use, weighed separately epoxy resin (Part A) & Hardener (Part B) as per the specified quantity in the mixing ratio & mix to uniform consistency & apply.
- Mix small quantity at a time, so that the mixed material is consumed within a work life time.
- Higher temperature and large quantity will shorten work life time.

For use of cartridge with Dispending gun

- Remove cap from tips. Affix static mixer.
- Insert cartridge into applicator gun.
- Pull trigger and epoxy will mix properly as it is dispensed.

Working

- Working time and cure time depends on temperature and mass:
- The higher the temperature, the faster the cure.
- The larger the mass of the material mixed, the faster the cure.
- To speed the cure of epoxies at low temperatures:
  - Store epoxy at room temperature.
  - Pre-heat repair surface until warm to the touch.
- To slow the cure of epoxies at high temperatures:
  - Mix epoxy in small masses to prevent rapid curing.
  - Cool resin/hardener component(s).

Packing

My-T-Bond® 2738 is available in 50 ml, 200ml and 400 ml dual cartridge. Also available in 1 kg and 5 kg packing containers

Storage and Handling

- Store product in a cool and dry location in Unopened containers at room temperature
- Keep away from moisture, direct sunlight & heat.
- Shelf Life 6 months in original sealed container when stored as above.
- To prevent contamination of unused product, do not return any material to its original container. For further specific information, contact our technical service centre.

Note

All statements, technical information and recommendations set forth herein are based on tests which Metlok Private Limited, believes to be reliable. However, Metlok Private Limited does not guarantee their accuracy or completeness. We cannot assume responsibility for the results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein and to adopt such precautions as may be advisable for the protection of property and of persons against any hazards that may be involved in the handling and use thereof. In no case will Metlok Private Limited be liable for direct, consequential economic or other damages.

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